

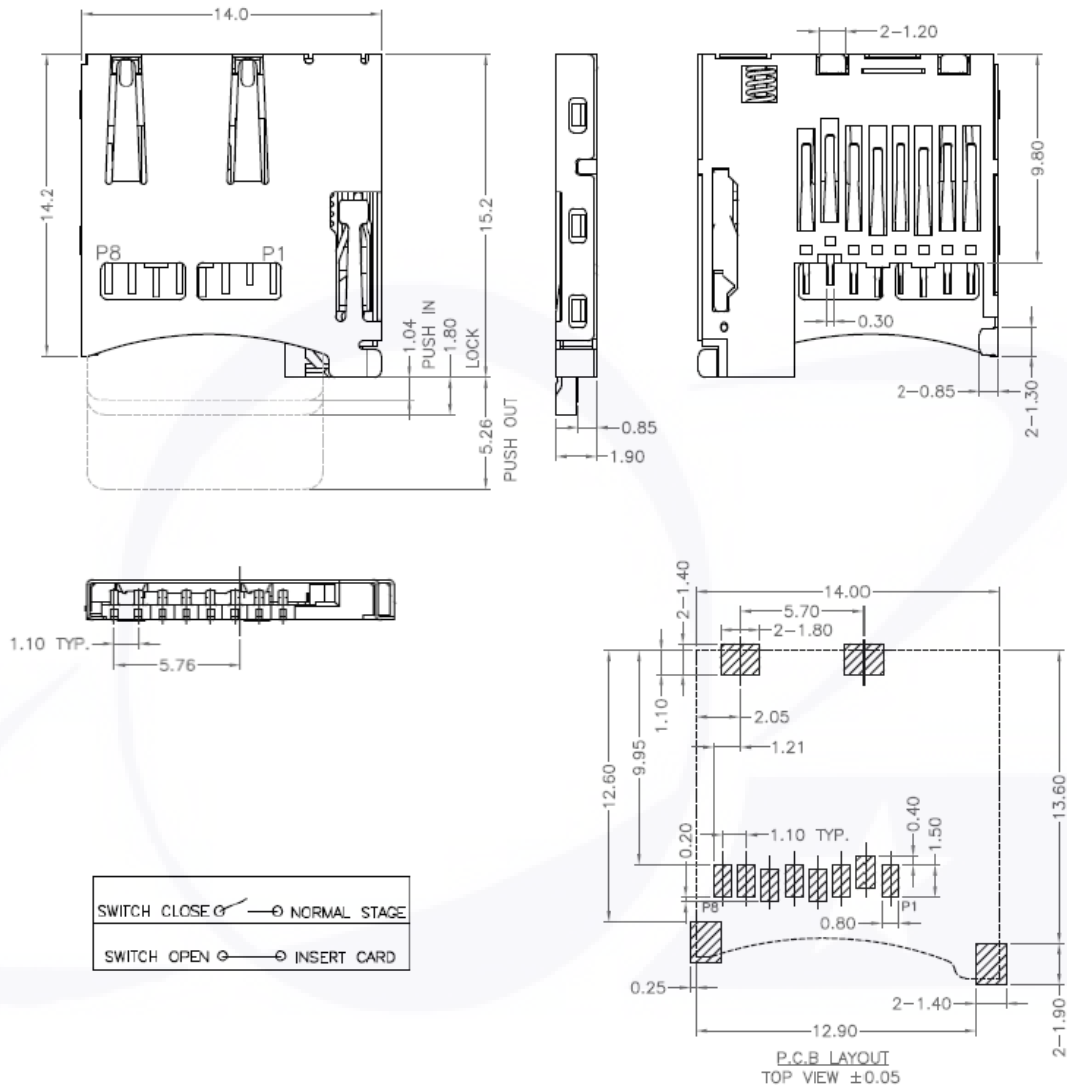
MICRO SD (T-FLASH) PCB MOUNT SMT METAL SHIELD FEMALE PUSH-PUSH TYPE

**MATERIALS**

HOUSING: HI-TEMP. PLASTIC, UL 94V-0  
 SHELL: STAINLESS STEEL  
 SOLDER PAD: COPPER ALLOY, TIN PLATING  
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA  
 TIN PLATING ON SOLDER TAIL

**SPECIFICATION**

CURRENT RATING: 0.5 AMP MAX  
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE  
 CONTACT RESISTANCE: 100m OHMS MAX  
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V  
 OPERATION TEMPERATURE: -20°C ~ +60°C



Series NO.	Free Code	NO. of Pos.	Contact	Contact Plating	Packing	Status
SDT-	1-	08	[2] SMT	[G1] Gold Flash	[R] Reel	[R] RoHS